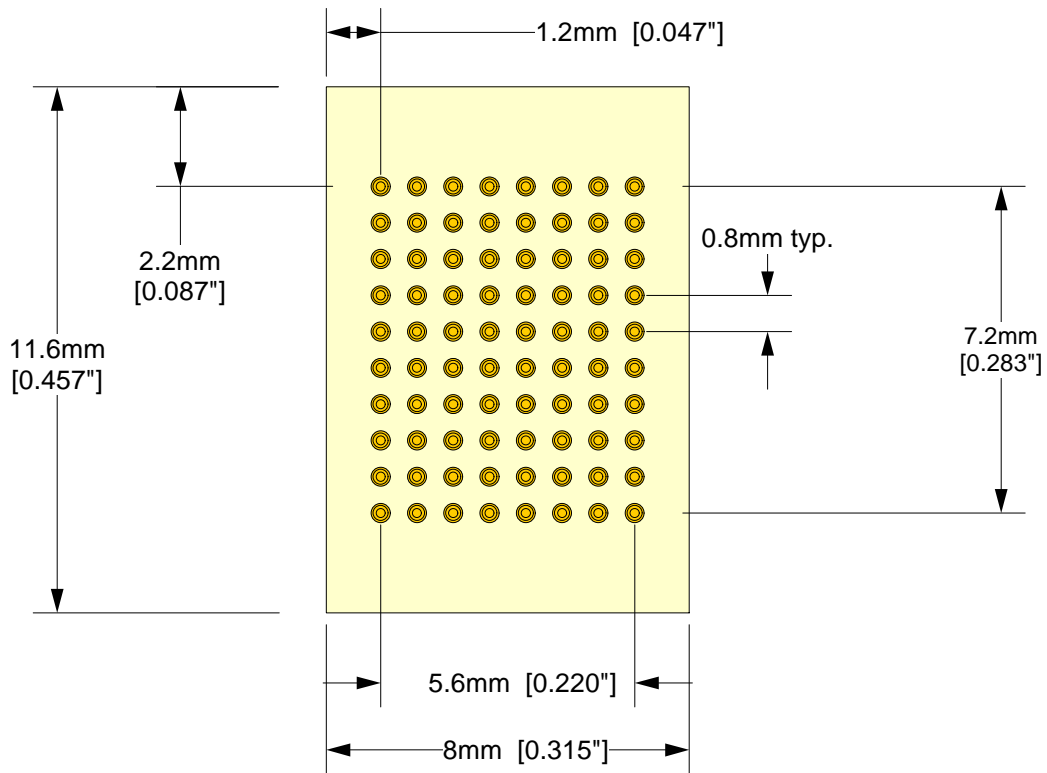
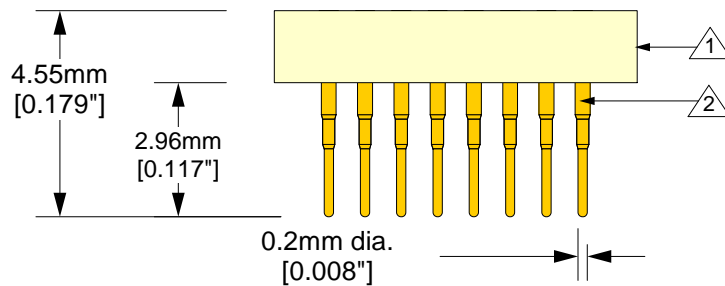


Top View



Side View




- ① Substrate: 1.59mm \pm 0.18mm [0.0625" \pm 0.007"] FR4/G10 or equivalent high temp material; Non-clad
- ② Pins: material- Brass Alloy 360 1/2 hard; finish- 0.25 μ m [10 μ " Au over 1.27 μ m [50 μ " Ni (min.).

Description: Giga-snaP BGA SMT Land Socket

80 position BGA surface mount land pattern to terminal pins (0.8mm centers, 8x10 array)

Tolerances: diameters \pm 0.03mm [\pm 0.001"], PCB perimeters \pm 0.13mm [\pm 0.005"], PCB thicknesses \pm 0.18mm [\pm 0.007"], pitches (from true position) \pm 0.08mm [\pm 0.003"], all other tolerances \pm 0.13mm [\pm 0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.

 <p>© 2007 IRONWOOD ELECTRONICS, INC. 11351 Rupp Drive, Suite 400, Burnsville, MN 55337 Tele: (952) 229-8200 www.ironwoodelectronics.com</p>	<p>LS-BGA80L-61 Drawing</p>	<p>Status: Released</p>	<p>Scale: 6:1</p>	<p>Rev: C</p>
	<p>Drawing: J. Glab</p>	<p>Date: 7/27/07</p>	<p>File: LS-BGA80L-61 Dwg.mcd</p>	<p>Modified: 01/18/13</p>